Product / Process Change Notification



N° 2015-055-A

Dear Customer,

Please find attached our INFINEON Technologies PCN:

Conversion to Copper Wire Bond for PG-DSO-8 products: TLE4253GS, TLE4254GA, TLE4254GS and TLF2931G V50

Important information for your attention:

- Please respond to this PCN by indicating your decision on the approval form, sign it and return to your sales partner before 06. June 2016.
- Infineon aligns with the widely-recognized JEDEC STANDARD "JESD46", which stipulates: "Lack of acknowledgement of the PCN within 30 days constitutes acceptance of the change."

Your prompt reply will help Infineon Technologies to assure a smooth and well executed transition. If Infineon does not hear from your side by the due date, we will assume your full acceptance to this proposed change and its implementation.

Your attention and response to this matter is greatly appreciated.

Disclaimer:

If we do not receive any response within the given time limit we consider this as the acceptance of the PCN.

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SUBJECT OF CHANGE: Conversion to Copper Wire Bond

PRODUCTS AFFECTED:	Type TLF2931G V50 TLE4254GS TLE4254GA TLE4253GS	SP n° SP000848484 SP001098846 SP001098844 SP001134938	OPN TLF2931GV50XUMA1 TLE4254GSXUMA3 TLE4254GAXUMA3 TLE4253GSXUMA3	Package PG-DSO-8 PG-DSO-8 PG-DSO-8 PG-DSO-8
OBSOLETE PRODUCTS: (These products are already switched to DOPL 8" products above)	Type TLE4254GS	SP n° SP000297353 SP001133412	OPN TLE4254GSXUMA1 TLE4254GSXUMA2	Package PG-DSO-8 PG-DSO-8
	TLE4254GA TLE4253GS	SP000297354 SP001133416 SP000253854	TLE4254GAXUMA1 TLE4253GSXUMA2 TLE4253GSXUMA1	PG-DSO-8 PG-DSO-8 PG-DSO-8

REASON OF CHANGE: Copper wire bonding is part of Infineon's continuous drive to deliver

higher performance products. A copper wire enables superior

electrical, thermal and reliability performance compared to Au, making it an excellent interconnect solution for automotive packaging.

The change of glue to Ablebond is part of an overall alignment

strategy.

DESCRIPTION OF CHANGE:	<u>OLD</u>	<u>NEW</u>
■ Die attach	EN 4900	Ablebond
■ Bondwire	30μ Αυ	30μ Cu
■ SP numbers	SP000848484 (TLF2931G V50) SP001098846 (TLE4254GS) SP001098844 (TLE4254GA)	SP001370956 (TLF2931G V50) SP001370964 (TLE4254GS) SP001370966 (TLE4254GA)
	SP001134938 (TLE4253GS)	SP001370962 (TLE4253GS)

PRODUCT IDENTIFICATION: Different ordering codes are used for the new products.

TIME SCHEDULE:

Final qualification report:	available	
First samples available:	available	
■ Intended start of delivery:	31-October-2016	or earlier after customer release

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ASSESSMENT: No impact on electrical performance. Quality and reliability verified by

qualification.

There is no change in form, fit and function of package material beside

bondwire material and die attach

REMARK: Please note that 3 PCNs have been released:

For product TLE4254GS please refer to PCN 2013-066 For product TLE4254GA please refer to PCN 2014-108 For product TLE4253GS please refer to PCN 2014-129

These PCNs contains the DOPL 8inch transfer. If you release these PCNs, please have in mind that you will get 8 inch products. For the 8 inch variant you should use samples from PCN 2015-055 for qualification, because the old 8 inch products (Au wire) will be

discontinued.

DOCUMENTATION: Overview on former changes on affected products including the PCN

and announcing the new product. Please see table below.

Sales Product	DOPL_6"-VI Au-bondwire	DOPL_6"-VI Cu-bondwire	DOPL_8"-KU Au-bondwire	DOPL_8"-KU Cu-bondwire
TLF2931G V50	SP000848484	SP001370956		
	PCN 2015-055			
	Obsolete products:			
TLE4254GS	SP000297353 SP001133412 PCN 2013-066		SP001098846 PCN 2015-055	SP001370964
TLE4254GA	SP000297354 PCN 2014-108		SP001098844 PCN 2015-055	SP001370966
TLE4253GS	SP001133416 SP000253854 PCN 2014-129		SP001134938 PCN 2015-055	SP001370962

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